ON Semiconductor®

Product Bulletin

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Issue Date:22 Apr 2020

Title of Change:	AR1337 Die Datasheet Update.
Effective date:	22 Apr 2020
Contact information:	Contact your local ON Semiconductor Sales Office or Sonya.Yip@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Documentation Change
Change Sub-Category(s):	Datasheet/Product Doc change

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
None	None

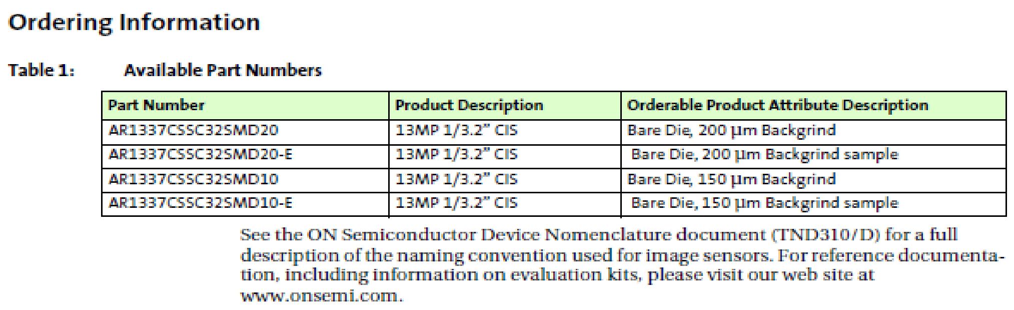
Description and Purpose:

The AR1337 Die Datasheet has been converted to official ON Semiconductor format and updated. These changes do not affect form, fit, or function of the product.

AR1337 Die Datasheet Changes

1. Updated Table 1, “Available Part Numbers” to reflect currently available Ordering Part Numbers

Old Table 1:



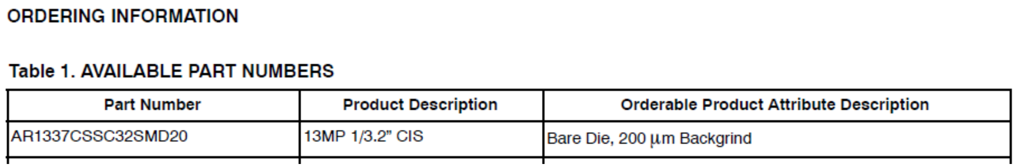
Ordering Information

Table 1: Available Part Numbers

Part Number	Product Description	Orderable Product Attribute Description
AR1337CSSC32SMD20	13MP 1/3.2” CIS	Bare Die, 200 μm Backgrind
AR1337CSSC32SMD20-E	13MP 1/3.2” CIS	Bare Die, 200 μm Backgrind sample
AR1337CSSC32SMD10	13MP 1/3.2” CIS	Bare Die, 150 μm Backgrind
AR1337CSSC32SMD10-E	13MP 1/3.2” CIS	Bare Die, 150 μm Backgrind sample

See the ON Semiconductor Device Nomenclature document (TND310/D) for a full description of the naming convention used for image sensors. For reference documentation, including information on evaluation kits, please visit our web site at www.onsemi.com.

New Table 1:



ORDERING INFORMATION

Table 1. AVAILABLE PART NUMBERS

Part Number	Product Description	Orderable Product Attribute Description
AR1337CSSC32SMD20	13MP 1/3.2” CIS	Bare Die, 200 μm Backgrind

2. Removed 150 mm ± 12 μm from “Table 4, Physical Dimensions”

Old Table 4:

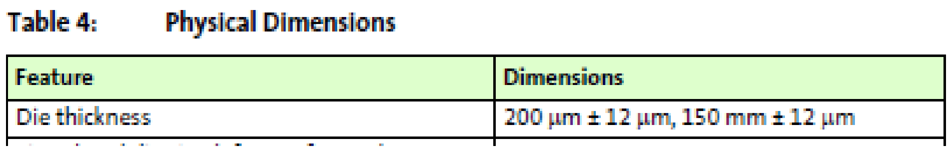


Table 4: Physical Dimensions

Feature	Dimensions
Die thickness	200 μm ± 12 μm, 150 mm ± 12 μm

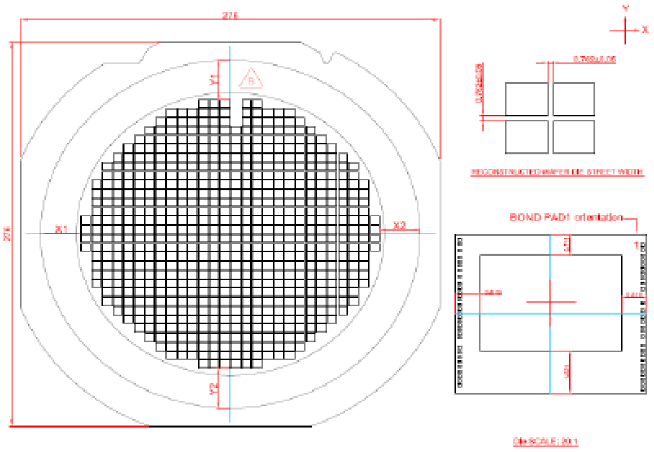
New Table 4:

Table 4. PHYSICAL DIMENSIONS

Feature	Dimensions
Die thickness	200 µm ± 12 µm

3. Removed "Figure 3. Die Orientation in Reconstructed Wafer, 150 µm thickness"

Figure 3: Die Orientation in Reconstructed Wafer, 150 µm thickness



Singulated die size:
Width: 6,300 µm ±25 µm
Length: 5,700 µm ±25 µm
Reconstructed wafer
street width: 762 µm
Maximum number of rows: 30
Maximum number of columns: 28
Dicing tape: Adwill D-175
Film frame: Disco
Maximum total die count: 629

List of Affected Standard Parts:

***Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

AR1337CSSC32SMD10
AR1337CSSC32SMD20